

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP WHITE ,UL94V-0.
- 1.2 CONTACT: COPPER ALLOY,GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS,80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING:0.5A;
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 50V AC/MINUTE.
- 2.3 CONTACT RESISTANCE: 50mΩ MAX.
- 2.4 INSULATION RESISTANCE: 100MΩ MIN.
- 2.5 OPERATION TEMPERATURE:-20°C TO +105°C.

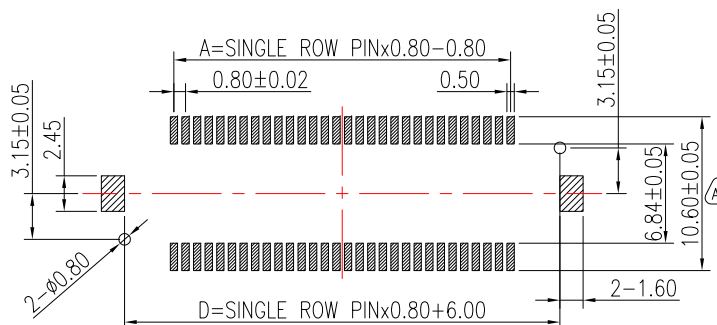
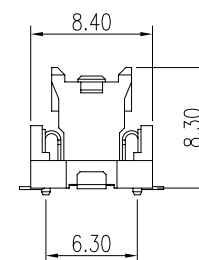
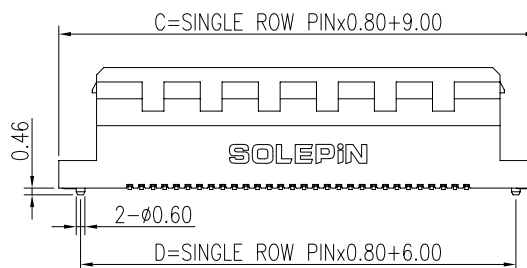
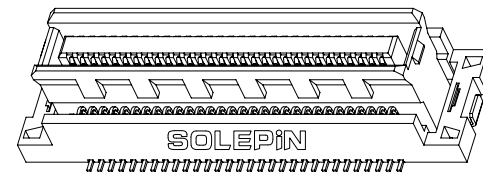
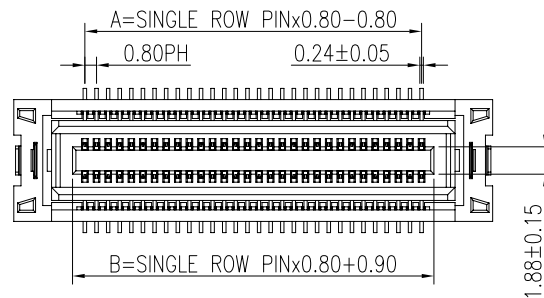
3.ORDER INFORMATION:

66C8-F XXX XX 083 R 01

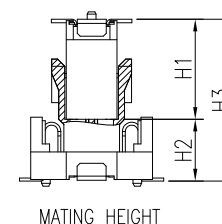
Pin数码	端子电镀:	塑胶高度:	包装方式:
020:2x10PIN	G0=Gold Flash	083=8.30mm	R=TAPE REEL
.....	G1=1u" Gold		
100:2x50PIN	G2=3u" Gold		
	G3=5u" Gold		
	G4=10u" Gold		
	G5=15u" Gold		
	G6=30u" Gold		

TABLE1:

No. OF PIN	A	B	C	D
010=2x05PIN	3.20	4.90	13.00	10.00
020=2x10PIN	7.20	8.90	17.00	14.00
030=2x15PIN	11.20	12.90	21.00	18.00
040=2x20PIN	15.20	16.90	24.00	22.00
050=2x25PIN	19.20	20.90	29.00	26.00
060=2x30PIN	23.20	24.90	33.00	30.00
080=2x40PIN	31.20	32.90	41.00	38.00
100=2x50PIN	39.20	40.90	49.00	46.00
120=2x60PIN	43.20	44.90	53.00	50.00



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05



MATING HEIGHT	H1	H2	H3
11.75mm	6.80	4.95	11.75
12.75mm	7.80		12.75

OPERATION	DRAW	WLY	2021.06.21	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
X.X ±0.40	DESIGN	Jensen	2021.06.21				
X.XX ±0.25	CHECK	Jack	2021.06.21				
X.XXX ±0.15	APPROVE	Andy	2021.06.21	SIZE	A4	PART NO.	66C8-FXXXXX083R01
Angle ±3°				SHEET	1/1	TITLE:	浮动BTB PH0.80mm 母座直立式SMT H8.3mm
DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-366

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
A1	2021.06.21	PIN针焊盘宽度由10.34修改为10.60	WLY	
AO		NEW		

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: PA9T WHITE ,UL94V-0.
- 1.2 CONTACT: COPPER ALLOY,GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS,80u" MIN. MATTE TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING:0.5A;
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 50V AC/MINUTE.
- 2.3 CONTACT RESISTANCE: 50mΩ MAX.
- 2.4 INSULATION RESISTANCE: 100MΩ MIN.
- 2.5 OPERATION TEMPERATURE:-20°C TO +105°C.

3.ORDER INFORMATION:

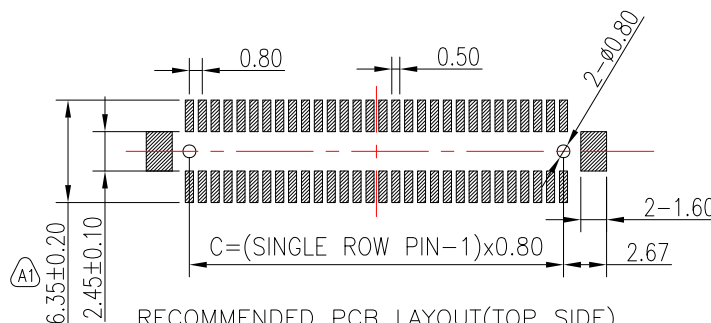
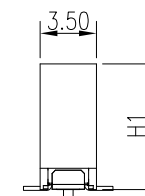
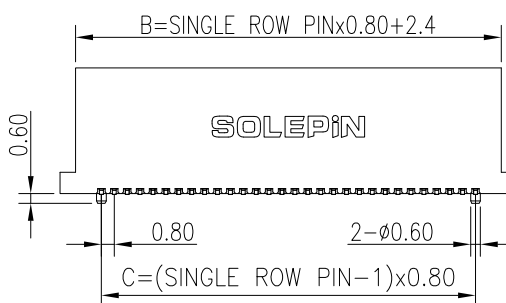
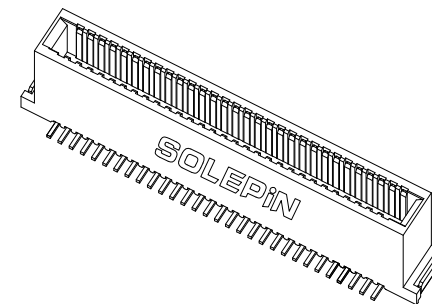
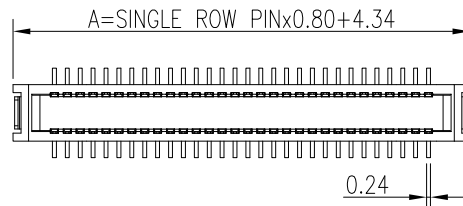
66C8-M XXX XX XXX R 01

Pin数码
008:2x10PIN
.....
120:2x60PIN

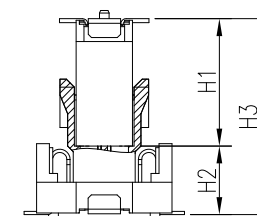
端子电镀:
G0=Gold Flash
G1=1u" Gold
G2=3u" Gold
G3=5u" Gold
G4=10u" Gold
G5=15u" Gold
G6=30u" Gold

塑胶高度:
068=6.80mm("H1")
078=7.80mm("H1")

包装方式:
R=TAPE REEL



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCE ±0.05



MATING HEIGHT

TABLE1:

No.OF PIN	Dimensions		
	A	B	C
010=2*05PIN	8.34	6.40	3.20
020=2*10PIN	12.34	10.40	7.20
030=2*15PIN	16.34	14.40	11.20
040=2*20PIN	20.34	18.40	15.20
050=2*25PIN	24.30	22.40	19.20
060=2*30PIN	28.34	26.40	23.20
080=2*40PIN	36.34	34.40	31.20
100=2*50PIN	44.34	42.40	39.20
120=2*60PIN	52.34	50.40	47.20

MATING HEIGHT	H1	H2	H3
11.75mm	6.80	4.95	11.75
12.75mm	7.80		12.75

					OPERATION		DRAW		WLY		2021.06.21		SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD				
					X.X	±0.40	DESIGN		Jensen		2021.06.21						
A1	2021. 06. 21	PIN针焊盘宽度由5. 95修改为6. 35		WLY		X.XX	±0.25	CHECK		Jack		2021.06.21		SIZE	A4	PART NO.	66C8-MXXXXXXXXR01
A0		NEW		_____	_____	X.XXX	±0.15	APPROVE		Andy		2021.06.21		SHEET	1/1	TITLE:	浮动BTB PH0.80mm 公头直立式SMT TYPE
						Angle	±3°										
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.	SP-319	

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
A1	2021.06.21	PIN针焊盘宽度由5.95修改为6.35	WLY	
A0		NEW		